FAIRCHILD

SEMICONDUCTOR®

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74ACTQ541
Quiet Series Octal Buffer/Line Driver with 3-STATE Outputs

Features

- I_{CC} and I_{OZ} reduced by 50%
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Guaranteed pin-to-pin skew AC performance
- Inputs and outputs on opposite sides of package for easy board layout
- Non-inverting 3-STATE outputs
- Guaranteed 4kV minimum ESD immunity
- TTL compatible inputs
- Outputs source/sink 24mA

General Description

The 74ACTQ541 is an octal buffer/line driver designed to be employed as memory and address drivers, clock drivers and bus oriented transmitter/receivers.

This device is similar in function to the 74ACTQ244 while providing flow-through architecture (inputs on opposite side from outputs). This pinout arrangement makes this device especially useful as an output port for micro-processors, allowing ease of layout and greater PC board density.

The 74ACTQ541 utilizes FACT Quiet Series™ technol-ogy to guarantee quiet output switching and improved dynamic threshold performance. FACT Quiet Series features GTO™ output control and undershoot corrector in addition to split ground bus for superior performance.
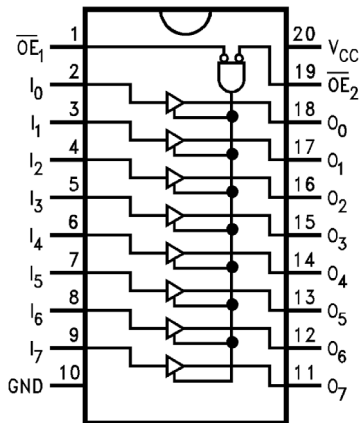
Ordering Information

Order Number	Package Number	Package Description
74ACTQ541SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ACTQ541MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.
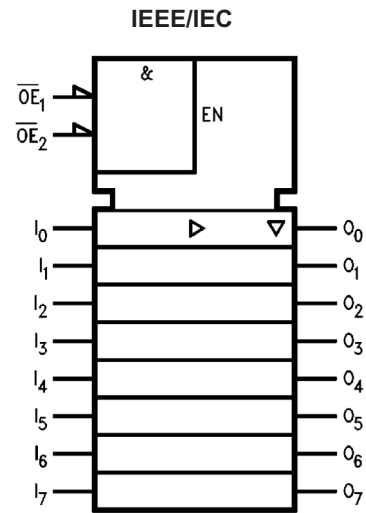
All packages are lead free per JEDEC: J-STD-020B standard.

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Connection Diagram

Logic Symbol

IEEE/IEC

Pin Description

Pin Name	Pin Description
$\overline{OE}_1$–$\overline{OE}_2$	3-STATE Output Enable (Active-LOW)
I_0–I_7	Inputs
O_1–O_7	Outputs

Truth Table

Inputs			
$\overline{OE}_1$	$\overline{OE}_2$	I	Outputs
L	L	H	H
H	X	X	Z
X	H	X	Z
L	L	L	L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +7.0V
I_{IK}	DC Input Diode Current $V_I = –0.5V$ $V_I = V_{CC} + 0.5V$	 –20mA +20mA
V_I	DC Input Voltage	–0.5V to V_{CC} + 0.5V
I_{OK}	DC Output Diode Current $V_O = –0.5V$ $V_O = V_{CC} + 0.5V$	 –20mA +20mA
V_O	DC Output Voltage	–0.5V to V_{CC} + 0.5V
I_O	DC Output Source or Sink Current	±50mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Output Pin	±50mA
T_{STG}	Storage Temperature	–65°C to +150°C
	DC Latch-Up Source or Sink Current	±300mA
T_J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	4.5V to 5.5V
V_I	Input Voltage	0V to V_{CC}
V_O	Output Voltage	0V to V_{CC}
T_A	Operating Temperature	–40°C to +85°C
$\Delta V / \Delta t$	Minimum Input Edge Rate: V_{IN} from 0.8V to 2.0V, V_{CC} @ 4.5V, 5.5V	125mV/ns

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C Typ.	Guaranteed Limits	T_A = −40°C to +85°C Guaranteed Limits	Units
V_{IH}	Minimum HIGH Level Input Voltage	4.5	V_{OUT} = 0.1V or V_{CC} − 0.1V	1.5	2.0	2.0	V
		5.5		1.5	2.0	2.0	
V_{IL}	Maximum LOW Level Input Voltage	4.5	V_{OUT} = 0.1V or V_{CC} − 0.1V	1.5	0.8	0.8	V
		5.5		1.5	0.8	0.8	
V_{OH}	Minimum HIGH Level Output Voltage	3.0	I_{OUT} = −50μA	2.99	2.9	2.9	V
		4.5		4.49	4.4	4.4	
		4.5	V_{IN} = V_{IL} or V_{IH}, I_{OH} = −24mA[1]		3.86	3.76	
		5.5			4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	3.0	I_{OUT} = 50μA	0.002	0.1	0.1	V
		4.5		0.001	0.1	0.1	
		4.5	V_{IN} = V_{IL} or V_{IH}, I_{OH} = 24mA[1]		0.36	0.44	
		5.5			0.36	0.44	
I_{IN}	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND		±0.1	±1.0	μA
I_{OZ}	Maximum 3-STATE Leakage Current	5.5	V_I = V_{IL}, V_{IH}; V_O = V_{CC}, GND		±0.25	±2.5	μA
I_{CCT}	Maximum I_{CC}/Input	5.5	V_I = V_{CC} − 2.1V	0.6		1.5	mA
I_{OLD}	Minimum Dynamic Output Current[2]	5.5	V_{OLD} = 1.65V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85V Min.			−75	mA
I_{CC}	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND		4.0	40.0	μA
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	5.0	Figures 1 & 2[3]	1.1	1.5		V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	5.0	Figures 1 & 2[3]	−0.6	−1.2		V
V_{IHD}	Minimum HIGH Level Dynamic Input Voltage	5.0	[4]	1.9	2.2		V
V_{ILD}	Maximum LOW Level Dynamic Input Voltage	5.0	[4]	1.2	0.8		V

Notes:

1. All outputs loaded; thresholds on input associated with output under test.

2. Maximum test duration 2.0ms, one output loaded at a time.

3. Max number of outputs defined as (n). Data inputs are driven 0V to 3V. One output @ GND.

4. Max number of Data Inputs (n) switching. (n–1) Inputs switching 0V to 5V (ACQ). Input-under-test switching: 5V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), f = 1MHz.

AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)[5]	T_A = +25°C, C_L = 50pF			T_A = −40°C to +85°C, C_L = 50pF		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, Data to Output	5.0	2.0	4.5	7.0	2.0	7.5	ns
t_{PHL}			2.0	5.5	7.0	2.0	7.5	
t_{PZH}	Output Enable Time	5.0	2.0	5.0	9.0	2.0	9.5	ns
t_{PZL}			2.0	6.5	9.0	2.0	9.5	
t_{PHZ}	Output Disable Time	5.0	1.5	5.5	7.5	1.5	8.0	ns
t_{PLZ}			1.5	5.5	7.5	1.5	8.0	
t_{OSHL}	Output to Output Skew, Data to Output[6]			0.5	1.0		1.0	ns
t_{OSLH}				0.5	1.0		1.0	

Notes:

5. Voltage Range 5.0 is 5.0V ± 0.5V

6. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

Capacitance

| Symbol	Parameter	Conditions	Typ.	Units
C_{IN}	Input Capacitance	V_{CC} = OPEN	4.5	pF
C_{PD}	Power Dissipation Capacitance	V_{CC} = 5.0V	70	pF

FACT Noise Characteristics

The setup of a noise characteristics measurement is critical to the accuracy and repeatability of the tests. The following is a brief description of the setup used to measure the noise characteristics of FACT.

Equipment:

Hewlett Packard Model 8180A Word Generator

PC-163A Test Fixture

Tektronics Model 7854 Oscilloscope

Procedure:

1. Verify Test Fixture Loading: Standard Load 50pF, 500Ω.

2. Deskew the HFS generator so that no two channels have greater than 150ps skew between them. This requires that the oscilloscope be deskewed first. It is important to deskew the HFS generator channels before testing. This will ensure that the outputs switch simultaneously.

3. Terminate all inputs and outputs to ensure proper loading of the outputs and that the input levels are at the correct voltage.

4. Set the HFS generator to toggle all but one output at a frequency of 1MHz. Greater frequencies will increase DUT heating and effect the results of the measurement.

5. Set the HFS generator input levels at 0V LOW and 3V HIGH for ACT devices and 0V LOW and 5V HIGH for AC devices. Verify levels with an oscilloscope.
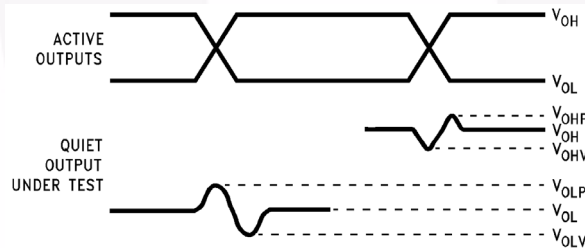
Notes:

7. V_{OHV} and V_{OLP} are measured with respect to ground reference.

8. Input pulses have the following characteristics:
   $f = 1MHz$, $t_r = 3ns$, $t_f = 3 s$, skew $< 150ps$.

Figure 1. Quiet Output Noise Voltage Waveforms

V_{OLP}/V_{OLV} and V_{OHP}/V_{OHV}:

■ Determine the quiet output pin that demonstrates the greatest noise levels. The worst case pin will usually be the furthest from the ground pin. Monitor the output voltages using a 50Ω coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.

■ Measure V_{OLP} and V_{OLV} on the quiet output during the worst case transition for active and enable. Measure V_{OHP} and V_{OHV} on the quiet output during the worst case active and enable transition.

■ Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

V_{ILD} and V_{IHD}:

■ Monitor one of the switching outputs using a 50Ω coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.

■ First increase the input LOW voltage level, V_{IL}, until the output begins to oscillate or steps out a min of 2ns. Oscillation is defined as noise on the output LOW level that exceeds V_{IL} limits, or on output HIGH levels that exceed V_{IH} limits. The input LOW voltage level at which oscillation occurs is defined as V_{ILD}.

■ Next decrease the input HIGH voltage level, V_{IH}, until the output begins to oscillate or steps out a min of 2ns. Oscillation is defined as noise on the output LOW level that exceeds V_{IL} limits, or on output HIGH levels that exceed V_{IH} limits. The input HIGH voltage level at which oscillation occurs is defined as V_{IHD}

■ Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability on the measurements.
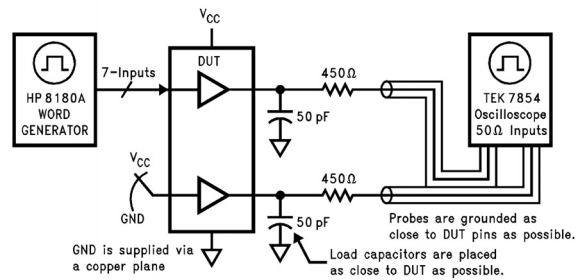

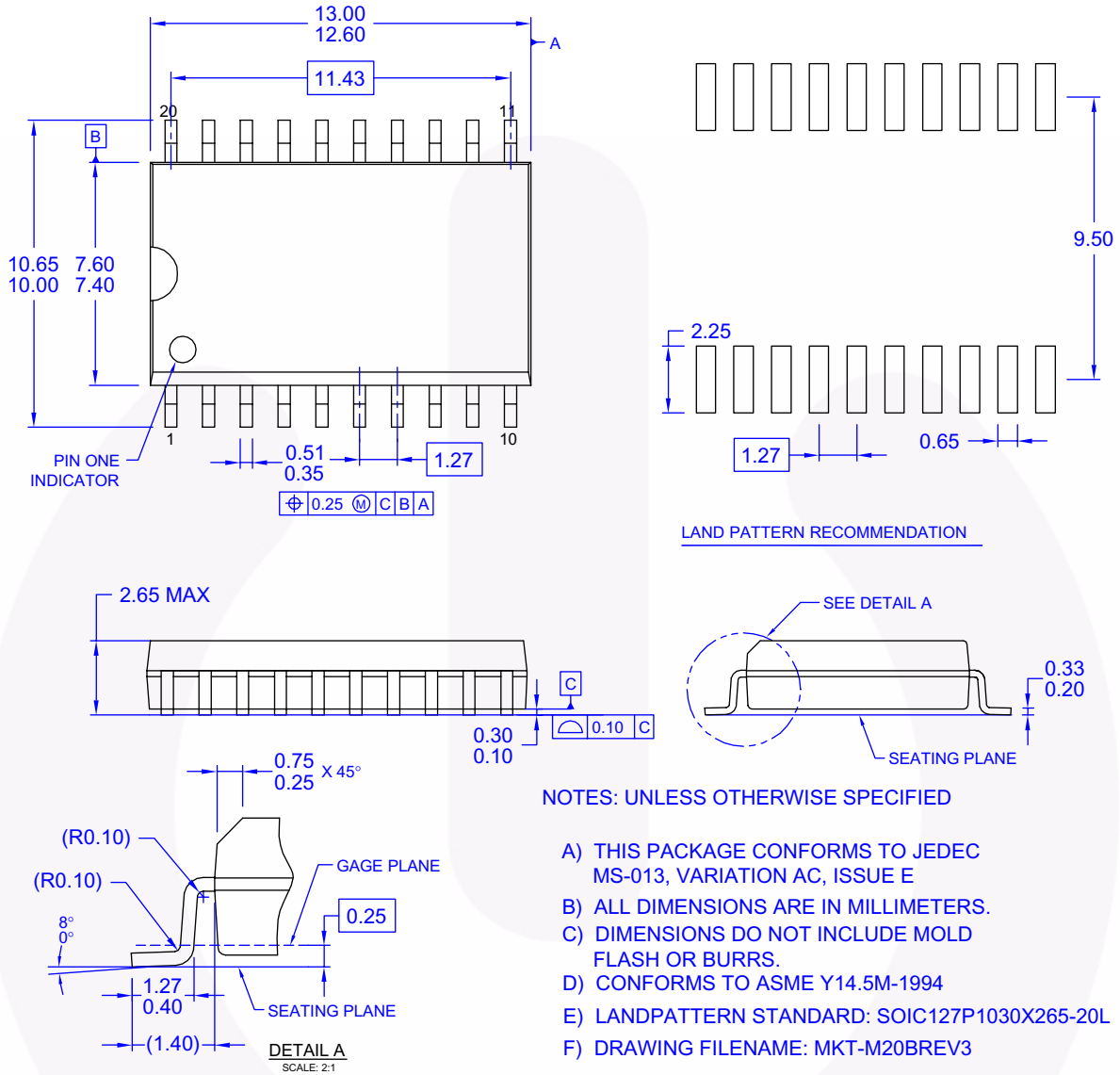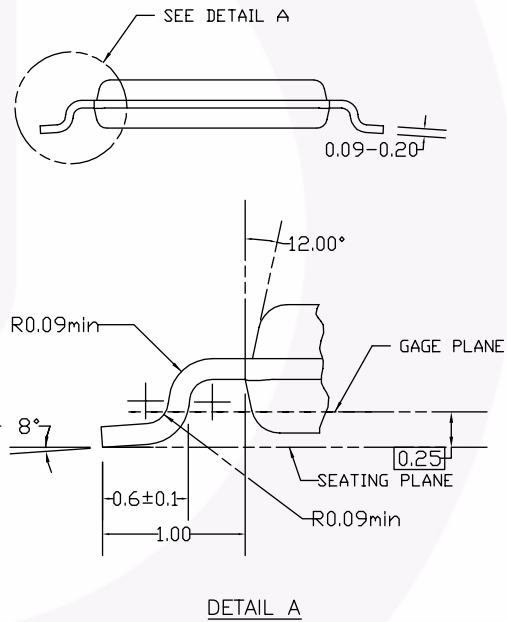**Figure 2. Simultaneous Switching Test Circuit**

Physical Dimensions

13.00
12.60

11.43

A

B

20

11

10.65   7.60
10.00   7.40

9.50

2.25

1

10

PIN ONE
INDICATOR

0.51
0.35

1.27

⊕ | 0.25 Ⓜ | C | B | A

1.27

0.65

LAND PATTERN RECOMMENDATION

2.65 MAX

C

0.30
0.10

⌒ | 0.10 | C

SEE DETAIL A

0.33
0.20

SEATING PLANE

0.75
0.25   X 45°

(R0.10)

(R0.10)

GAGE PLANE

0.25

8°
0°

1.27
0.40

SEATING PLANE

(1.40)

DETAIL A
SCALE: 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC
    MS-013, VARIATION AC, ISSUE E
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE MOLD
    FLASH OR BURRS.
D) CONFORMS TO ASME Y14.5M-1994
E) LANDPATTERN STANDARD: SOIC127P1030X265-20L
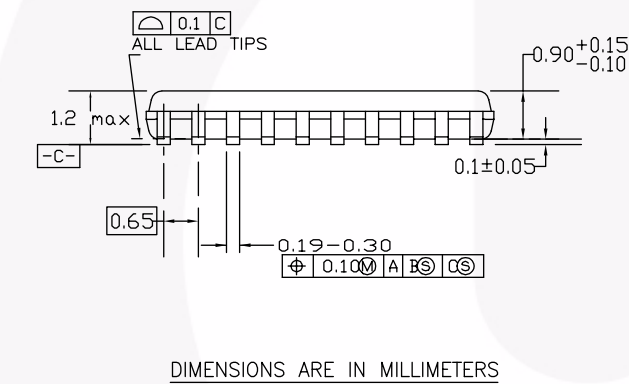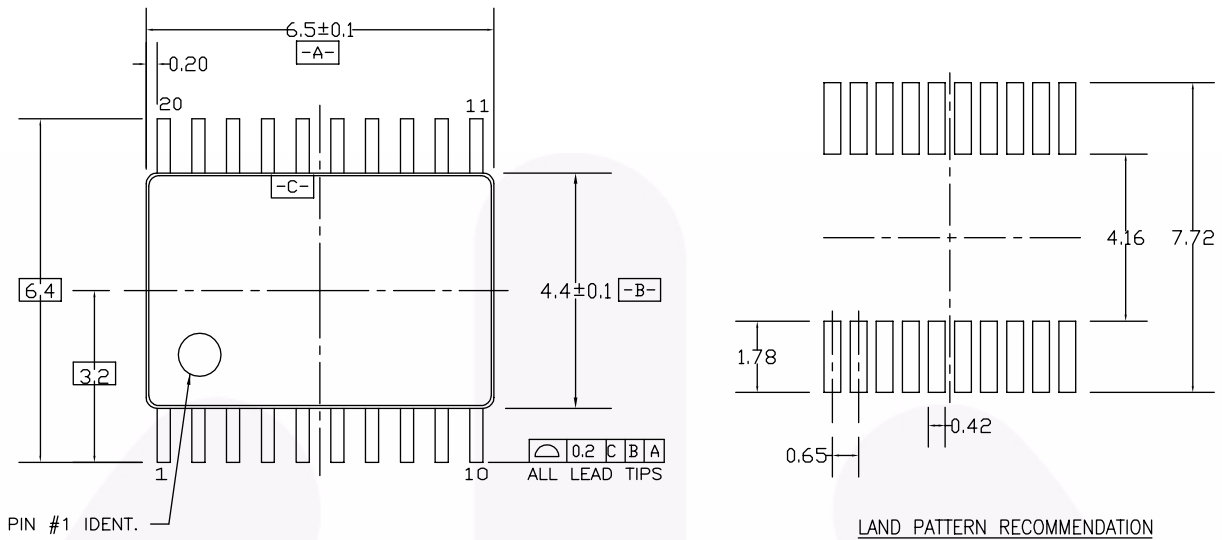F) DRAWING FILENAME: MKT-M20BREV3

Figure 3. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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Physical Dimensions (Continued)

6.5±0.1
-A-

-0.20

20   11

-C-

6.4

4.4±0.1 -B-

3.2

△ 0.2 C B A
ALL LEAD TIPS

1   10

PIN #1 IDENT.

LAND PATTERN RECOMMENDATION

4.16   7.72

1.78

0.65   0.42

△ 0.1 C
ALL LEAD TIPS

0.90 +0.15 -0.10

1.2 max

-C-

0.1±0.05

0.65

0.19-0.30

⊕ 0.10Ⓜ A Ⓑ Ⓒ Ⓢ

DIMENSIONS ARE IN MILLIMETERS

SEE DETAIL A

0.09-0.20

12.00°

R0.09min

GAGE PLANE

0 - 8°

0.6±0.1

SEATING PLANE

0.25

R0.09min

1.00

DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

Figure 4. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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
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